



Call for Papers for Software Engineering Symposiums (SEPA & ISSQ in LNCS by Springer, TTSDP in IEEE Xplore)@ICCSA 2022, July 04-07, 2022, University of Malaga, Spain.

SUBMISSION DATE: 17.04.2022, Submission Site: <http://ess.iccsa.org/cqi-bin/login.py>

Request: May I kindly request you to submit your paper(s) and circulate the following CFP in your department, Software/Computer Science/ICT research groups, and all interested researchers who may be potential authors. All the publications will be in LNCS(Springer) as a book series of Computational Science and Its Applications: **ICCSA** and IEEE Xplore. Please visit the following site for more detail.

Any author who needs sufficient time for applying for funding will provide reviews within 30 days. Please inform us after submission.

14th International Symposium on Software Engineering Processes and Applications (SEPA)-2022 (Publication in LNCS by Springer):

<https://sites.google.com/view/ssepa/home>

<http://www.wikicfp.com/cfp/servlet/event.showcfp?eventid=154905©ownerid=3644>

13th International Symposium Software Quality- (ISSQ)-2022-Publish in LNCS by Springer

<https://sites.google.com/view/issq/home>

<http://www.wikicfp.com/cfp/servlet/event.showcfp?eventid=154908©ownerid=3644>

14th Int Workshop on Tools and techniques in Software Development Processes (TTSDP)- 2022(Publication in IEEE Xplore):

<http://www.wikicfp.com/cfp/servlet/event.showcfp?eventid=154910©ownerid=3644>

<https://sites.google.com/site/tandtinsdp/home>

If your paper is a theme paper and 10-16 pages long (LNCS Format), belongs/related to general and applications area of software engineering (e.g.-application or use of software/model/algorithms/tools/frameworks in clouds, IoT, healthcare, security, etc. and Software Intelligent systems), please submit it in Software Engineering process and applications (SEPA 2022). If you are working in any area related to quality issues of Software/Software engineering, consider Software Quality (ISSQ 2022) for your submission. Further, if your paper is a short session paper and up to 6-10 pages (in IEEE format), please select TTSDP 2022 for your submission.

The extended version (minimum 50% in technical content) of SEPA 2022, SQ 2022, and TTSDP 2022 papers will be accepted by Several Journals (all in SCOPUS/ESCI & **best papers in SCIE Indexed Journal-confirmed**).

The website for submission is open at the following link- <http://ess.iccsa.org/>.

While submitting your paper, don't forget to select the only - SEPA/ISSQ/TTSDP 2022.

I hope and request your contribution.

Prof Sanjay Misra, Organizing Chair: SEPA 2022, ISSQ-2022, TTSDP-2022

ssopam@gmail.com,

Editor In Chief: International Journal of Human Capital and Information Technology Professionals(IGI Global) (IJHCITP), "Advances in IT Personnel and Project Management (AITPPM)" (IGI Global USA), International Journal of Physical Sciences, Covenant J. of ICT (An official Journal of Cov Uni.).